



## Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard  
<http://www.ipc.org/ContentPage.aspx?pageid=Materials-Declaration>

Form Type\*  
Distribute

**Declaration Class\***  
**Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information**

### Supplier Information

<b>Company Name *</b> <b>Fairchild Semiconductor</b>	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	<b>Response Date*</b> <b>Sep 25, 2014 01:10 PM</b>
<b>Contact Name *</b> <b>David Lancaster</b>	Title - Contact Product Ecology	<b>Phone - Contact *</b> <b>801-562-7455</b>	<b>Email - Contact *</b> <b>david.lancaster@fairchildsemi.com</b>
<b>Authorized Representative *</b> <b>David Lancaster</b>	Title - Representative Product Ecology	<b>Phone - Representative *</b> <b>801-562-7455</b>	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
FDMS7660AS	FDMS7660AS	PQFN-8 (TFSnCuAlBW).csv			FSCP	<b>0.105956</b>	g	Each

### Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Sn	Copper Alloy	1	260 C	30 seconds	3

\* Required Field

RoHS Material Composition Declaration		Declaration Type * Custom
<b>RoHS Directive</b> 2011/65/EU	<b>RoHS Definition:</b> Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium	
<p>This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.</p> <p>The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.</p> <p>Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.</p>		
<b>RoHS Declaration *</b> <b>4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions</b> <b>Supplier Acceptance * Accepted</b>		
<b>Exemptions:</b> If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.		
Exemption List Version EL-2011/534/EU 7(a) Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).		

Declaration Signature	
Supplier Signature	<div style="text-align: center;">  </div> <div style="text-align: center; font-size: small; margin-top: 5px;">DAVID LANCASTER - PRODUCT ECOLOGY MANAGER</div>

## Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name PQFN-8 (TFSnCuAlBW).csv

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	5.09	Supplier		Silicon	5.09	7440-21-3	48039
Die Attach	Other Nonferrous metals & alloys	6.941	A	Lead/Lead Compounds	Lead	6.42	7439-92-1	60591
			Supplier		Silver	0.174	7440-22-4	1642
			Supplier		Tin	0.347	7440-31-5	3275
Encapsulation	Thermoplastics	44.4	Supplier		Carbon Black	0.444	1333-86-4	4190
			Supplier		Epoxy Resin	2.22	29690-82-2	20952
			Supplier		Metal Hydroxide - Generic CAS#	2.22	G0007	20952
			Supplier		Phenolic resin	1.332	9003-35-4	12571
			Supplier		Silica, vitreous	38.184	60676-86-0	360375
Lead Frame	Copper & its alloys	35.434	Supplier		Copper	34.5	7440-50-8	325606
			Supplier		Iron	0.85	7439-89-6	8022
			Supplier		Silver	0.038	7440-22-4	361
			Supplier		Zinc	0.046	7440-66-6	434
Terminal Finish	Other Nonferrous metals & alloys	13.5	Supplier		Tin	13.5	7440-31-5	127411
Wire Bond	Copper & its alloys	0.591	Supplier		Aluminum	0.584	7429-90-5	5511
			Supplier		Copper	0.007	7440-50-8	67